

ABSTRACT OF THE DISCLOSURE

A method of manufacturing an epoxy resin composition for semiconductor encapsulating by use of a kneader provided with a suction hole on the downstream side of a kneading region in a conveying direction of the epoxy resin composition, and being provided with a supply orifice and a discharge orifice respectively disposed on the upstream side and the downstream side in the conveying direction of the epoxy resin composition, the method comprising kneading the epoxy resin composition, while discharging a volatile gas from the kneader through the suction hole, and simultaneously introducing outside air to the kneader through the supply orifice and the discharge orifice. Even under conditions of continuous operation of the kneader, it is possible to efficiently discharge a volatile gas, thereby significantly decreasing the quantity of a volatile components remaining in the kneaded epoxy resin composition. Therefore, when semiconductor devices are encapsulated with the epoxy resin composition, the generation of voids can be decreased.